

## CC2564-PAN1326

SWRS124 - JULY 2012

# Dual Mode *Bluetooth<sup>®</sup>* Smart Ready

#### FEATURES

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- Best-In-Class Bluetooth RF Performance (Tx Power, Rx Sensitivity, Blocking)
- TX: +10 dBm, Rx: -93 dbM
- Fully Qualified *Bluetooth* v4.0 + Enhanced Data Rate (EDR)
- Dimensions PAN1326: 9 mm x 9.5 mm x 1.8 mm (Width x Length x Height)
- Dimensions PAN1316: 6.5 mm x 9.5 mm x 1.8 mm (Width x Length x Height)
- Certification: FCC, IC, CE
- Operating Temperature Range: -20°C to 70°C
- Supply Voltage Range: 1.7 V 4.8 V
- Profiles:
  - Serial Port Profile (SPP)
  - Generic Attribute Profile (GATT)
  - Alert Notification Profile (ANP)
  - Alert Notification Service (ANS)
  - Device Information Service (DIS)
  - Health Thermometer Profile (HTP)
  - Health Thermometer Service (HTS)
  - Heart Rate Profile (HRP)
  - Heart Rate Service (HRS)
- Integrates With TI's Ultra Low-Power MSP430<sup>™</sup> Microprocessor
- Fast Algorithm for Both ACL and eSCO
- Supports Extended Range Tx Power With 10 dBm Typical Output
- Low Power Scan Method for Page and Inquiry Scans at 1/3rd Normal Power

### **APPLICATIONS**

- Sport and Fitness
- Watches
- Mobile Accessories
- Entertainment Devices
- Toys
- All Bluetooth Wireless Application

#### DESCRIPTION

The following product brief applies to Panasonic's *Bluetooth* module, series number: PAN1326 and PAN1316. The *Bluetooth* chip used is based on the CC2564 from Texas Instruments.

The CC2564-PAN1326 and PAN1316 enables *Bluetooth* Low Energy and Bluetooth connectivity in a broad spectrum of devices. This device aims to lower the consumption of power while establishing fast connection for the transfer for small amount of data. While in sleep mode, less than 135  $\mu$ A of power is consumed and the overall power consumption is around 40 mA. CC2564-PAN1326 and PAN1316 device maintains best-in-class *Bluetooth* RF performance.

Similar to CC2567-PAN1327 and PAN1317 which enables a dual mode for ANT and **Bluetooth**, this device is supported to run a dual mode for *Bluetooth* and *Bluetooth* Smart (Low Energy). For evaluations use the PAN1323EMK, MSP-EXP4305438 Experimenter Board, and MSP-FET430UIF (each sold separately).

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